



Bridging the Broadband Divide  
9-13 June • Budapest, Hungary

# IEEE International Conference on Communications



## Patronage Brochure



# IEEE International Conference on Communications

The International Conference on Communications (ICC) is one of the two flagship conferences of the IEEE Communications Society, together with IEEE GLOBECOM. Each year the IEEE ICC conference attracts about 3,000 submitted scientific papers, a technical program committee involving about 1,500 experts provides more than 10,000 reviews, and the conference is finally attended by 1,500 – 2,000 professionals from all around the world. IEEE ICC is therefore one of the most significant scientific events of the networking and communications community, a must-attend forum for both industrials and academics working in this area.

## Conference Program

The IEEE ICC conference is a five-day event, three days being dedicated to the technical symposia and two days to tutorials and workshops. The program of the technical symposia includes oral and poster presentations of about 1,000 scientific papers, grouped into 12 thematic tracks, and 18 to 20 parallel sessions. In addition, the conference program includes workshops, tutorials, keynote talks from industrial leaders and renowned academics, panel discussions and a large exhibition.

	Sunday, 9 June	Monday, 10 June	Tuesday, 11 June	Wednesday, 12 June	Thursday, 13 June
09.00–10.30	Tutorials & workshops	Opening Words, Keynote 1	Keynotes 2-3	Ind. (1) Tech (20) Post. (1)	Tutorials & workshops
11.00–12.30	Tutorials & workshops	Ind. (1) Tech (20) Post. (1)	Ind. (1) Tech (20) Post. (1)	Ind. (1) Tech (20) Post. (1)	Tutorials & workshops
12.30–14.00	Lunch	Lunch	Awards Lunch	Lunch	Lunch
14.00–15.30	Tutorials & workshops	Ind. (1) Tech (20) Post. (1)	Ind. (1) Tech (20) Post. (1)	Ind. (1) Tech (20) Post. (1)	Tutorials & workshops
16.00–17.30	Tutorials & workshops	Ind. (1) Tech (20) Post. (1)	Ind. (1) Tech (20) Post. (1)	Tech (20)	Tutorials & workshops
18.00–19.00		Wireless Futures & Hungarian Nibbles (Industrial) Panel			
19.00–20.00	Welcome Reception	Conference Banquet			
20.00–22.00					

Tut. & ws	Tutorials and workshops in parallel	Tech (20)	20 Technical sessions in parallel
Ind. (1)	1 Industrial panel	Post. (1)	1 Poster session

## Expected Participation

We expect about 1,500 participants from all over the world.

About 30 exhibition booths give enough space for presentations and demonstrations of recent advances in research and development.

In 2013 the IEEE ICC conference will be held for the first time in Eastern Europe.

More information: [www.ieee-icc.org/2013](http://www.ieee-icc.org/2013)

## History

Since 1965

2002 - New York, USA

2003 - Anchorage, Alaska, USA

2004 - Paris, France

2005 - Seoul, Korea

2006 - Istanbul, Turkey

2007 - Glasgow, Scotland

2008 - Beijing, China

2009 - Dresden, Germany

2010 - Cape Town, South Africa

2011 - Kyoto, Japan

2012 - Ottawa, Canada

# Patronage

## Patronage means leadership

- ◇ Your patronage validates the leadership of your organization in the industry and positions your company to gain maximum exposure with IEEE ICC 2013 attendees.
- ◇ Use this business-building event to share your company's products and services with important decision makers in the industry.
- ◇ Patron status maximizes your company's visibility and enhances your company's reputation.
- ◇ IEEE ICC 2013 gives you access to thousands of people that you want to reach and influence.
- ◇ Your company will be prominently featured as an IEEE ICC 2013 patron.
- ◇ Showcase your brand to the most influential engineering audience in communications technology.

## Why Become a Patron?

The IEEE ICC is the global, world-class event to present the most recent results from research, development and standardization.

The IEEE ICC brings together industry leaders and scientists from around the globe to debate, discuss and learn about the technologies, business opportunities and new applications.

Patrons enjoy extraordinary visibility with the powerful audience at the conference. There is no competition for time between conference sessions and networking receptions. The character of the event as a place where important ideas are exchanged is evident and continually reinforced throughout the event.

The IEEE ICC attracts the "Who's Who" in communications, i.e., leading customers, operators, vendors, researchers, investors and press. Attendees mingle in a relaxed environment, and discuss the future of communications with those who are shaping it.

Patrons gain access to research executives and directors of some of the world's leading R&D organizations and project representatives. The event's attendees are responsible for setting R&D and product development goals and have a considerable budget responsibility.

The IEEE ICC has a long track record and an increasingly powerful, loyal audience. Since 1965 it has a reputation as "major communications event".

We would welcome your own ideas for discussion, and would be glad to assist with any enquiries you may have. The wide range of opportunities available means that you can choose a package that fits your particular marketing strategy. Some opportunities are negotiable.

### Previous Patrons

#### IEEE ICC'12 Canada: Telus,

Alcatel-Lucent, Huawei,  
Algonquin College, Carlton University, Ciena,  
CISCO, Ericsson, IBM, Nokia Siemens Networks  
*Exfo, Fujitsu, IET, Juniper Networks, NetCracker,  
Oracle, RIM, Sigma, Subex*

#### IEEE ICC'10 South Africa: Telkom,

Huawei, Nokia Siemens Networks, Samsung, ICT  
Research, Development and Innovation Strategy  
for South Africa,  
*Alcatel-Lucent, CISCO, Dimension Data, ICASA,  
Logiways, SKT Construction, TFMC, Unisys,  
Vodacom*

#### IEEE ICC'09 Germany: Qualcomm,

CISCO, Deutsche Telekom, Dresden, NEC, Nokia  
Siemens Networks, Vodafone  
*DLR, Ericsson, Saxony State Ministry for Economic  
Affairs and Labour, Signalion, ST Ericsson,  
TU Dresden, Tektronix, UMTS Forum*

#### IEEE ICC'08 China: China Telecom, China Mobile, CNC, China Unicom, Huawei, ZTE,

Ericsson  
*Broadcom, France Telecom, Fujitsu, Nokia,  
Panasonic*

#### IEEE ICC'07 Scotland: Scottish Development International,

Scottish Enterprise,  
Picstel Technologies, Scottish Executive,  
Vodafone,  
*Alcatel-Lucent, Nokia Siemens Networks,  
Qualcomm*

#### IEEE ICC'06 Turkey: Turkcell,

Alcatel, Turk Telekom, Siemens, Tübitak,  
CISCO, eKom, Ericsson, Havelsan, HP, Karel,  
Nokia, Telenity

# Patronage Packages

## Overview

	Platinum	Gold	Silver	Bronze	Associate
Banner or roll-up with your company name and patronage level in the foyer area of the conference venue	X				
Your company name and patronage level listed on a display panel in the foyer area of the venue	X	X			
Company-flag / roll-up in front of the venue	6	3			
Keynote speech during conference (subject to approval by OC/TCP)	X				
Acknowledgement by the chairman during Welcome Reception, Opening and Banquet	Welcome, Opening, Banquet	Opening, Banquet			
Keynote address	X	X			
Full conference registrations and access to social events (#)	5	3	2		
Invitations to the exclusive „VIP” welcome reception (#)	3	2	1		
Advertisement in the Final Program (Full / half page)	Full page	Full	Half		
Patron’s material added to conference bag	X	X	X		
Complimentary 2m x 3m exhibition booths	Double size	Single size	Single size	Single size	
Listed on IEEE ICC 2013 conference website...					
- Your company logo	X	X	X	X	X
- Paragraph about the company/organization (up to #)	375 words	375	250	125	125
- Company/organization website URL	X	X	X	X	X

Available up to 

2	5	8
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## Patronage Packages

Platinum Patron Packages \$ 40,000  
 Gold Patron Packages \$ 20,000  
 Silver Patron Packages \$ 10,000  
 Bronze Patron Packages \$ 6,000  
 Associate Patron Packages \$ 3,500

## Special Patronage Packages

Please note that all patronage packages can be customized to suit your company’s preferences. In addition, there is a possibility to build patronage packages to include visibility at special program items like Conference Banquet, Awards Luncheon, Welcome Reception, Lunches, Coffee Breaks, etc., or through conference collateral like Final Program, Conference Bag, Proceedings and Lanyard. Please contact the organizers for more details.

More information: <http://www.ieee-icc.org/2013/patrons.html>

## Advertisement in the Final Program

The Final Program will contain all of the essential conference information and will be used as a reference guidebook well after the conference is over. Please note that the Full Conference Papers will be included in the Proceedings that the attendees will receive on USB sticks (no printed version).

Full page advertisement \$ 3,000

Half-page advertisement: \$ 2,000

# Exhibition

The IEEE ICC 2013 will take place at three luxurious 5-star hotels, Intercontinental, Marriott and Sofitel, situated one next to the other.

To broaden the diversity of the conference, the IEEE ICC 2013 provides an integrated exhibition area close to technical sessions, coffee areas and poster areas to ensure frequent attendance. This is an excellent chance to present your company and its recent results, as well as to get in touch with other young and senior scientists from industry and academia. In addition, to provide you the best possible benefit, the exhibition areas will be grouped by topic.

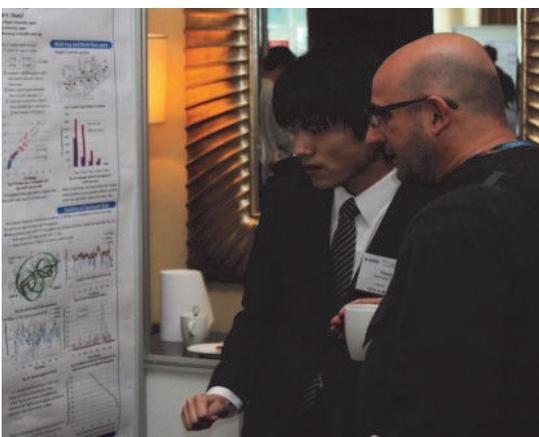


The following exhibition booth dimensions are offered:

- 2m x 3m \$ 3,000
- 2m x 6m \$ 5,000
- 2m x 9m \$ 7,000

Each booth is equipped with a power supply. Any furniture or additional equipment is subject to additional fees.

The actual placement of the exhibition booth is determined by the conference organizers.



We expect about 1500 participants from all over the world.

About 30 exhibition booths give enough space for presentations and demonstrations of recent advances in research and development.

## Exhibition Chair:

Nigel Jefferies

Huawei Technologies

e-mail: [nigel.jefferies@huawei.com](mailto:nigel.jefferies@huawei.com)

More information: [www.ieee-icc.org/2013/exhibitors.html](http://www.ieee-icc.org/2013/exhibitors.html)

# Conference Location

## About Hungary

Hungary is situated in the very heart of Europe. With a history going back more than 1100 years, it has joined the European Union in May 2004. The country has a size of ~36,000 sq mi (93,000 km<sup>2</sup>), which makes it similar in size to Indiana, South Korea or Portugal. It has a population of about 10 million inhabitants.

Hungary is rich in history and creativity – it's the birthplace of world-famous inventors, scientists, mathematicians, explorers, composers and sports stars. This is a place of variety, colour and passion.



## About Budapest



Budapest is the capital city of Hungary, and has a population of 1.7 million inhabitants. It is one of Europe's most beautiful cities, being often called "the pearl of the Danube".

The twin cities of Buda and Pest, divided by the Danube, united in 1873 to form the city of Budapest. Its architecture is characterized by homogenous parts of different building periods, such as vestiges of the Roman occupation, the prestigious Castle District preserved in Romanesque and Gothic style, the rigor of the Habsburg Citadel, the eclecticism of the turn-of-the-century buildings boasting the richness of the new citizens. It's truly a city where East meets West, and where people are historically familiar with both cultures, while their own culture and language remains unique. Visitors from all over the World feel at home here.



## Conference Venue



The IEEE ICC 2013 will take place at three luxurious 5-star hotels (Intercontinental, Marriott and Sofitel), situated one next to the other, in the very heart of the city, on the banks of the river Danube. The hotels offer a magnificent panorama on the river, the Gellert Hill and the Royal Castle District, a part of the UNESCO World Heritage. The maximum distance between the hotels is 300 meters (0.2 miles), which is an easy 5 minute walk.

More information: <http://www.ieee-icc.org/2013/information.html>



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WWW.IEEE-ICC.ORG/2013

## CALL FOR PAPERS

The 2013 IEEE International Conference on Communications (ICC) will be held in the vibrant city of Budapest, Hungary from 9 – 13 June 2013. This flagship conference of IEEE Communications Society aims at addressing an essential theme on “Bridging the Broadband Divide.” The conference will feature a comprehensive technical program including several Symposia and a number of Tutorials and Workshops. IEEE ICC 2013 will also include an attractive expo program including keynote speakers, various Business, Technology and Industry fora, and vendor exhibits. We invite you to submit your original technical papers, industry forum, workshop, and tutorial proposals to this event. Accepted and presented papers will be published in the IEEE ICC 2013 Conference Proceedings and in IEEE Xplore®. Full details of submission procedures are available at <http://www.ieee-icc.org/2013>.

To be published in the IEEE ICC 2013 Conference Proceedings and IEEE Xplore®, an author of an accepted paper is required to register for the conference at the full or limited (member or non-member) rate and the paper must be presented at the conference. Non-refundable registration fees must be paid prior to uploading the final IEEE formatted, publication-ready version of the paper. For authors with multiple accepted papers, one full or limited registration is valid for up to 3 papers. Accepted and presented papers will be published in the IEEE ICC 2013 Conference Proceedings and IEEE Xplore®.

### PLANNED TECHNICAL SYMPOSIA

#### Selected Areas in Communications Symposium

##### E-Health Area

Pradeep Ray, University of New South Wales, Australia

##### Power Line Communications Area

Andrea Tonello, University of Udine, Italy  
Stephan Weiss, University of Strathclyde, UK

##### Smart Grids Area

Bahram Honary, Lancaster University, UK

##### Tactical Communications & Operations Area

Gabe Jakobson, Altusys, USA

##### Satellite & Space Communication Area

Hiroimitsu Wakana, NICT, Japan

##### Data Storage Area

Tiffany Jing Li, Lehigh University, USA

##### Access Systems and Networks Area

Michael Peeters, Alcatel-Lucent, Belgium

##### Green Communication Systems and Networks

Athanassios Manikas, Imperial College London, UK

#### Wireless Communications Symposium

Zhaocheng Wang, Tsinghua University, China  
Metha B. Neelesh, Indian Institute of Science, India  
Hanna Bogucka, Poznan University of Technology, Poland  
Fredrik Tufvesson, Lund University, Sweden

#### Wireless Networking Symposium

Azzedine Boukerche, University of Ottawa, Canada  
Pan Li, Mississippi State University, USA  
Min Chen, Seoul National University, Korea

#### Communication Theory Symposium

David Gesbert, EURECOM, France  
Angel Lozano, Universitat Pompeu Fabra, Spain  
Vello Tralli, University of Ferrara, Italy  
Sennur Ulukus, University of Maryland, USA

#### Signal Processing for Communications Symposium

Hai Lin, Osaka Prefecture University, Japan  
Octavia Dobre, Memorial University, Canada  
Saiid Boussakta, Newcastle University, UK  
Hongyang Chen, Fujitsu Laboratories, Japan

#### Optical Networks and Systems Symposium

Xavier Masip-Bruin, Technical University of Catalonia, Spain  
Franco Callegati, University of Bologna, Italy  
Tibor Cinkler, Budapest University of Technology and Economics, Hungary

#### Next-Generation Networking Symposium

Malathi “MV” Veeraraghavan, University of Virginia, USA  
Joel Rodrigues, University of Beira Interior, Portugal  
Wojciech Kabacinski, Poznan University of Technology, Poland

#### Communication QoS, Reliability & Modeling Symposium

Tetsuya Yokotani, Mitsubishi Electric Corporation, Japan  
Harry Skianis, University of the Aegean, Greece  
Janos Tapolcai, Budapest University of Technology and Economics, Hungary

#### Ad-hoc and Sensor Networking Symposium

Guoliang Xue, Arizona State University, USA  
Abdallah Shami, University of Western Ontario, Canada  
Xinbing Wang, Shanghai Jiaotong University, China

#### Communication Software and Services Symposium

Jiangtao (Gene) Wen, Tsinghua University, China  
Lynda Mokdad, University Paris-Est, France

#### Communication and Information Systems Security Symposium

Tansu Alpcan, TU Berlin, Germany  
Mark Felegyhazi, Budapest University of Technology and Economics, Hungary  
Kejie Lu, University of Puerto Rico at Mayagüez, PR

#### Cognitive Radio and Networks Symposium

Honggang Zhang, Zhejiang University, China  
David Grace, University of York, UK  
Andrea Giorgetti, University of Bologna, Italy

### COMMITTEE

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**Christopher Mattheisen**  
CEO, Magyar Telekom, Hungary

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**Iain Collings**  
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**Wei Chen**  
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**Christina Fragouli**  
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**Peter Rost**  
NEC Labs Europe, Germany

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Sungkyunkwan University, Korea

**Peter Mueller**  
IBM Zurich Research Laboratory, Switzerland

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Budapest University of Technology and Economics, Hungary

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Universität der Bundeswehr München, Germany

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Germany

#### GITC Advisor:

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Asszisztencia, Hungary

#### Finance Chair:

**Peter Nagy**  
HTE, Hungary

#### Treasurer:

**Bruce Worthman**  
IEEE ComSoc, USA

### IMPORTANT DATES

Paper Submission  
16 September 2012

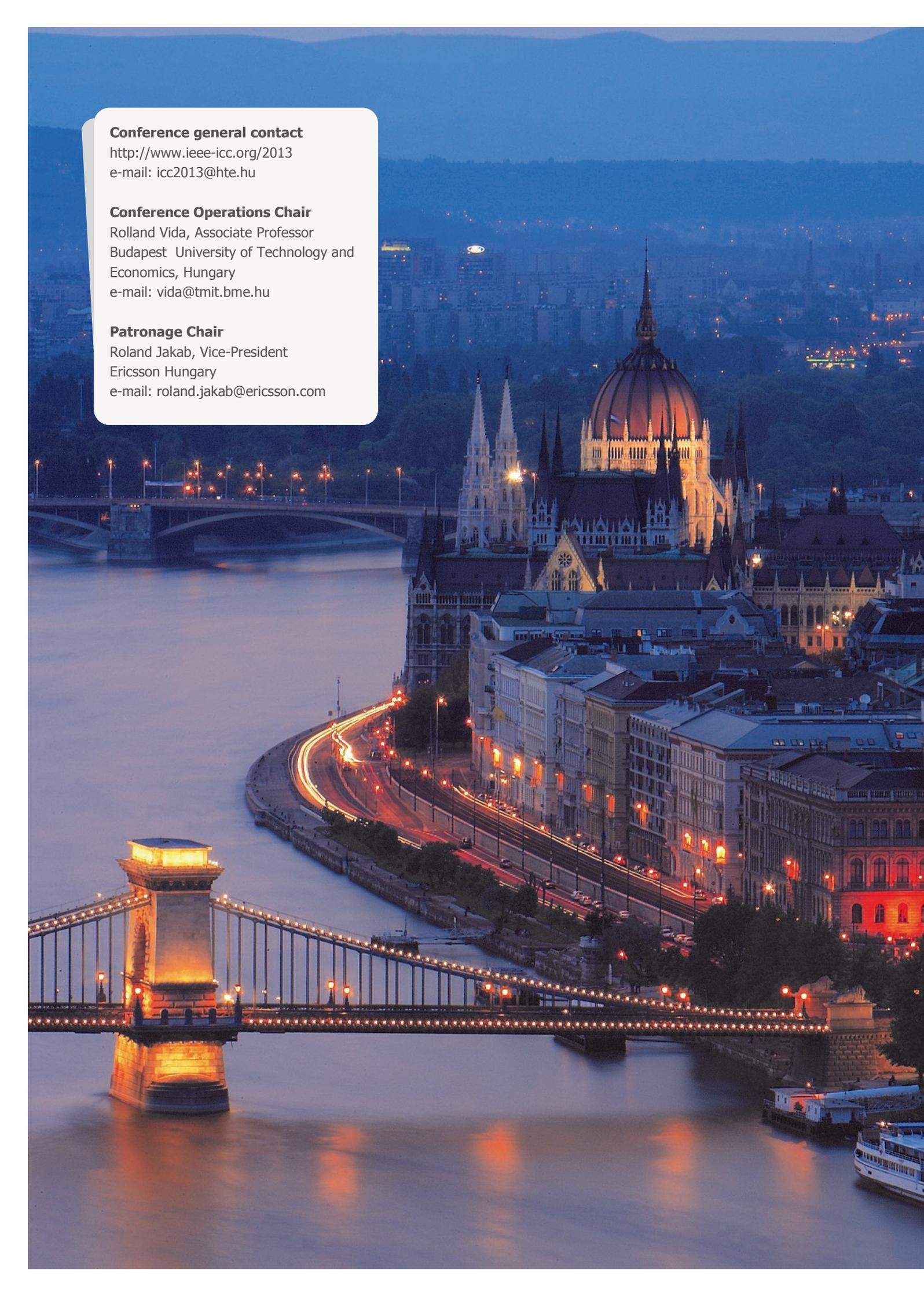
Acceptance Notification  
27 January 2013

Camera-Ready  
24 February 2013

Tutorial Proposal  
7 October 2012

Workshop Proposal  
25 June 2012

Business Forum Proposal  
8 April 2012

A nighttime photograph of Budapest, Hungary, featuring the illuminated Hungarian Parliament Building with its large dome and spires, and the Chain Bridge with its stone towers and suspension cables. The Danube River flows through the city, and the lights of the city buildings and streets are visible in the background.

**Conference general contact**

<http://www.ieee-icc.org/2013>

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**Conference Operations Chair**

Roland Vida, Associate Professor  
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**Patronage Chair**

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